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MN1380 Series

CMOS LSIs for Voltage Detection

Overview

The MN1380 series are elements that monitor the power supply voltage supplied to microcomputers and other LSI systems and issue reset signals for initializing the system after the power is first applied or for preventing runaway operation when the supply voltage fluctuates.

There is a choice of three output types: CMOS output, N-channel open drain output, and inverted CMOS output. There are also three package types: M, TO-92, and a mini type for surface mounting.

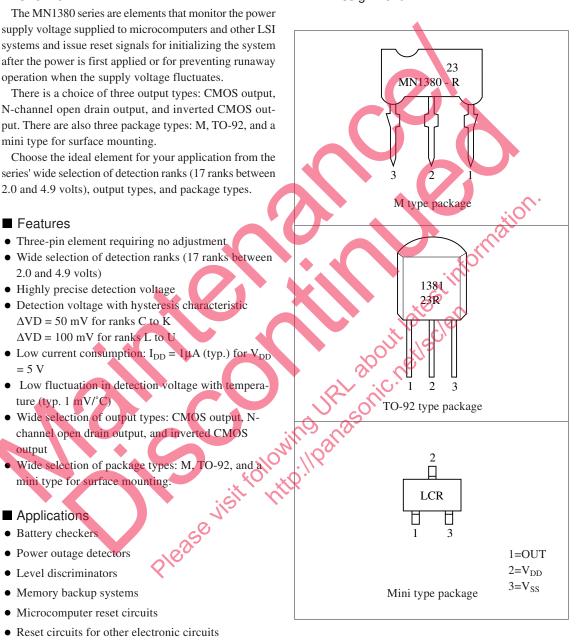
Choose the ideal element for your application from the series' wide selection of detection ranks (17 ranks between 2.0 and 4.9 volts), output types, and package types.

Features

- Three-pin element requiring no adjustment
- Wide selection of detection ranks (17 ranks between 2.0 and 4.9 volts)
- Highly precise detection voltage
- Detection voltage with hysteresis characteristic $\Delta VD = 50 \text{ mV}$ for ranks C to K $\Delta VD = 100 \text{ mV}$ for ranks L to U
- Low current consumption: $I_{DD} = 1 \mu A$ (typ.) for V_{DD}
- Low fluctuation in detection voltage with tempera-

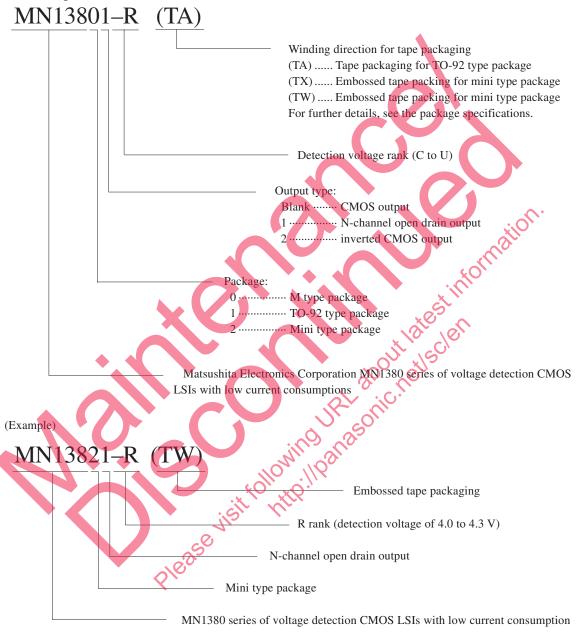
- · Microcomputer reset circuits
- Reset circuits for other electronic circuits

■ Pin Assignment



■ MN1380 Series Naming Conventions

The MN1380 series offers a wide selection of detection ranks, output types, package types, and packaging. All combinations use the following naming conventions. When ordering, be sure to give the correct part number using these naming conventions.



■ Minimum Packaging Unit

Bulk (M and TO-92 types) ·····	1,000
Magazine (Mini type) ·····	50
Taping (Mini and TO-92 types)	3,000

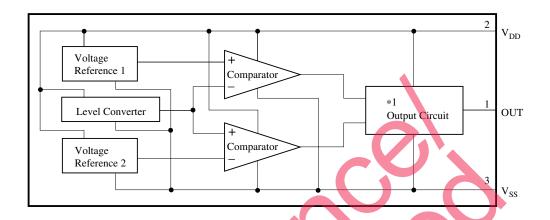
■ Series Lineup

Output Package	M type Package	TO-92 type Package	Mini type Package
CMOS output	MN1380	MN1381	MN1382
N-channel open drain output	MN13801	MN13811	MN13821
Inverted CMOS output	MN13802	MN13812	MN13822

■ Detection Ranks (on Voltage)

Rank	Detection Voltage for Drop in	Power Supply Voltage (V _{DL})	Unit	Detection Voltage	Hysteresis Width (ΔVD)	Unit
alik	min	max	Offic	min	max	OTIL
C	2.0	2.2				
D	2.1	2.3				
Е	2.2	2.4	V	50	300	mV
F	2.3	2.5	v	30	300	111 V
G	2.4	2.6				
Н	2.5	2.7				
J	2.6	2.9	V	50	300	mV
K	2.8	3.1		30	300	III V
L	3.0	3.3	1		aile	
M	3.2	3.5			Mile	
N	3.4	3.7			401	
P	3.6	3,9			tinformat	
Q	3.8	4.1	V	100	300	mV
R	4.0	4.3				
S	4.2	4.5		11,	COL	
Т	4.4	4.7		100 g		
U	4.6	4.9		Sp Up		
		3.5 3.7 3.9 4.1 4.3 4.5 4.7 4.9	rino.	JRY onio		

■ Block Diagram



Note *1: Circuits vary slightly depending on the output type (CMOS output, N-channel open drain output, or inverted CMOS output)

■ Pin Descriptions

Pin No.	Symbol	Function Description
1	OUT	Reset signal output pin
2	V_{DD}	Power supply pin
3	V _{SS}	Ground pin
		Power supply pin Ground pin A Country of the supply pin to the s

■ Absolute Maximum Ratings V_{SS}=0V, Ta=25°C

Parameter	Symbol	Rating	Unit
Power supply voltage	V_{DD}	7.0	V
Output voltage	V_{O}	-0.3 to $V_{\rm DD} + 0.3$	V
Operating ambient temperature	Ta	-20 to +70	°C
Storage temperature	$T_{\rm stg}$	-55 to +125	°C

■ Recommended Operating Conditions V_{SS}=0V, Ta=25°C

Parameter	Symbol	Conditions	min	typ	max	Unit
Power supply voltage	V _{DD}	See Figures 1 and 4.	1.5		6.0	V

■ Electrical Characteristics

1) DC Characteristics V_{SS} =0V, Ta=-20°C to +70°C

Parameter	Symbol	Cond	ditions	min	typ	max	Unit
Power supply current	I_{DD}	$V_{\rm DD}$ = 5 V *1				5	μA
		Load resistan	e = 10 kW			ين (μΑ
Detection voltage for drop	V_{DL}			*2		*2	v
in power supply voltage *2	, DL	Ta=25°C				W.	<u> </u>
Detection voltage hysteresis	ΔVD	See Figures 1	and 4.	*2		*2	mV
width *2	2,12						111 (
"H" level output voltage	V _{OH}	CMOS output	I _{OH} =-40μA	$0.8V_{\mathrm{DD}}$	xes ,	V_{DD}	
		Inverted	$V_{DD}=1.8V$	0.8	70	V_{DD}	V
		CMOS output	I_{OH} = $-0.5mA$	J'R	120,	-1.5	
"L" level output voltage	V _{OL}	N-channel open	$V_{DD}=1.8V$	V _{ss}		0.4	
		drain output	I _{OL} =0.7mA				v
		Inverted	V _{DD} =6.0V	V_{SS}		0.6	'
		CMOS output	I _{OH} =0.3mA)			
Notes			11/2010				
*1: This includes the output pin's	leakage cu	rrent.	W.100				
*2: For particulars, see the detect	ion voltage	rank table					
Notes *1: This includes the output pin's *2: For particulars, see the detect			Kill				
		iis"					
		.e					
	~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~	0					
Y	0/6						
	*						

■ Electrical Characteristics (continued)

2) AC Characteristics V_{SS}=0V, Ta=25°C

Parameter	Symbol	Cond	itione	All	lowable Value (t	yp)	Unit
raiailletei	Symbol	Cond	1110115	MN1380	MN13801	MN13802	Utill
			Donk	MN1381	MN13811	MN13812	
			Rank C	MN1382	MN13821	MN13822	
			D				
			Е	3.0	2.5	230.0	
			F				
			G				
		See	Н				
Reset release time	t _{OH}	Figures	J	3.0	3.0	100.0	μs
		2 and 3.	K				
			L				•
			M				
			N				-0.
			P			30.80 P	90,
			Q	2.0	4.0	30.0	
			R				
			S			in City	
			Т	•		CK!	
		XY	C		X	© ,	
						scler.	
			D	250.0	1000	50,	
			Е	250.0	160.0	3.0	
			F		(V. 1)		
			G		30100.100 m		
		See	Н				
Reset time	t _{OL}	Figures	J	115.0	100.0	3.0	μs
	• (2 and 3.	K	M11.00			
			L	110 1116			
			M	0, xx6.			
			N	Kr			
			N) P				
		250	Q	15.0	35.0	3.0	
		60	R				
			S				
			T				
			1				

■ Description of Operation

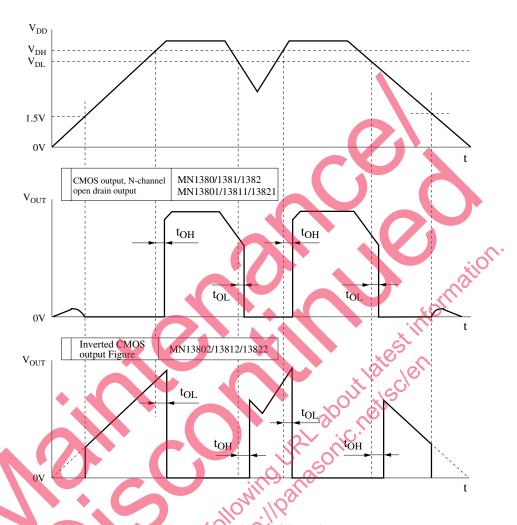


Figure 1. Description of Operation

Notes

- 1: Output cannot be specified for power supply voltages under 1.5 V because operation is not guaranteed for that range.
- 2: V_{DL}: Detection voltage for drop in power supply voltage
 - V_{DH}: Detection voltage for rise in power supply voltage
 - t_{OL} : Time lag between the time that the power supply voltage reaches the detection voltage $(V_{DL} \text{ or } V_{DH})$ and the time that the output pin (OUT) goes to "L" level.
 - t_{OH} : Time lag between the time that the power supply voltage reaches the detection voltage (V_{DL} or V_{DH}) and the time that the output pin (OUT) goes to "H" level.
- 3: These characteristics for the N-channel open drain output are when a load resistor is connected between the OUT and V_{DD} pins.

■ Description for Measuring the Output Characteristics

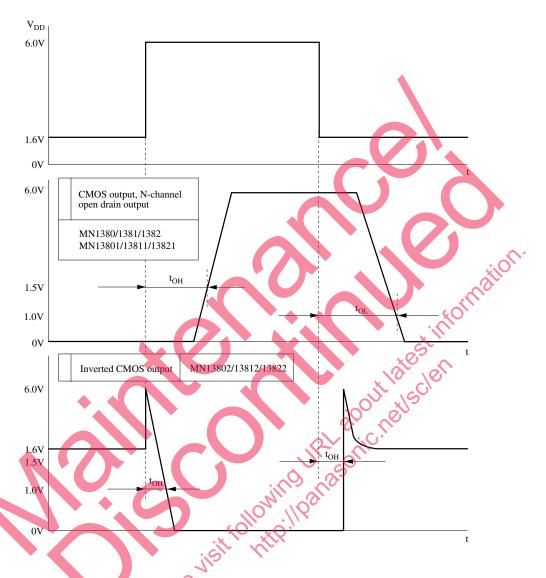


Figure 2. Description chart of Measuring the Output Characteristics

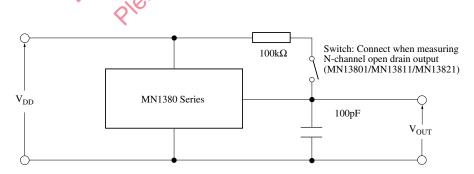


Figure 3. Circuit for Measuring the Output Characteristics

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■ Description for Measuring the I/O Characteristics

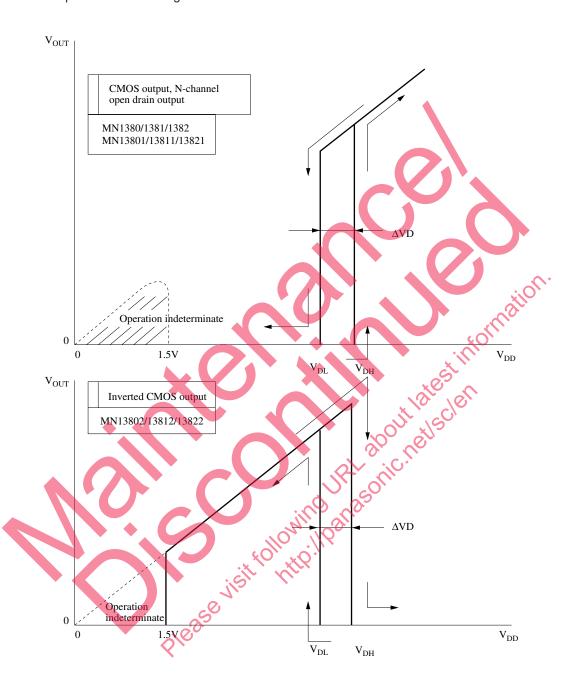


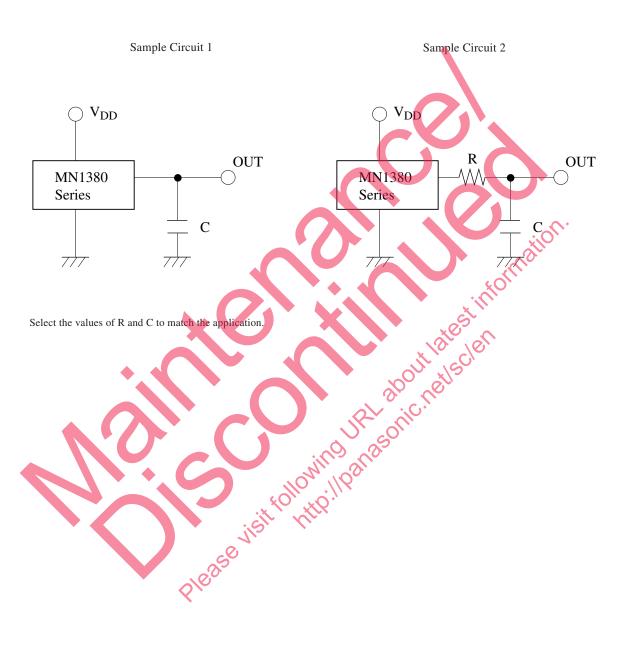
Figure 4. Description chart for Measuring the I/O Characteristics

Notes

- 1: Output cannot be specified for power supply voltages under 1.5 V because operation is not guaranteed for that range.
- 2: V_{DL}: Detection voltage for drop in power supply voltage
 - V_{DH} : Detection voltage for rise in power supply voltage
- 3: These characteristics for the N-channel open drain output are when a load resistor is connected between the OUT and V_{DD} pins.

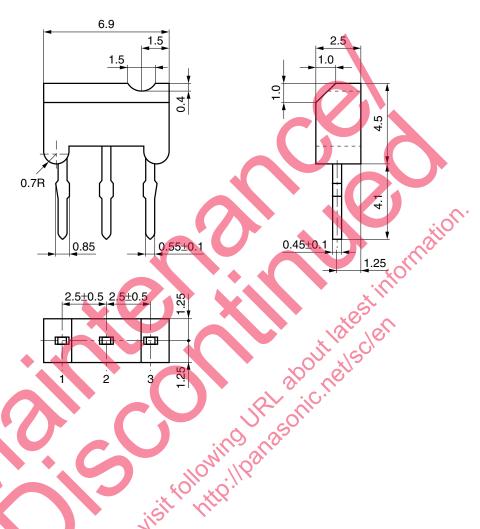
■ Application Circuit Example

Connect resistors, capacitors, and the like only to the output pin on the MN1380 series element. Note that connecting them to the Power source pins changes V_{DH} , V_{DL} , and ΔVD .



■ Package Dimensions (Unit: mm)

M type package



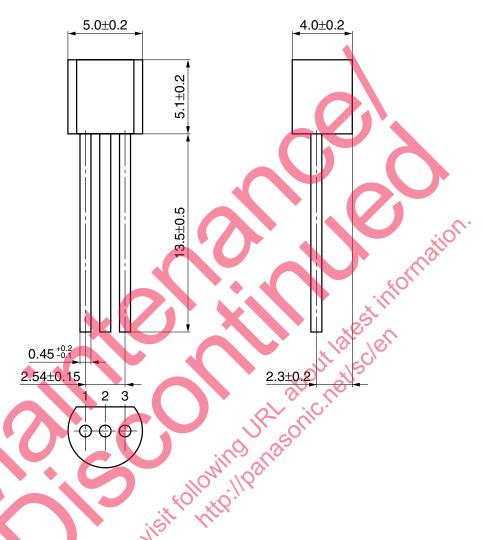
Note) The package will be changed to lead-free type (M3A). See the new package dimensions section later of this datasheet.

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■ Package Dimensions (Unit: mm)(continued)

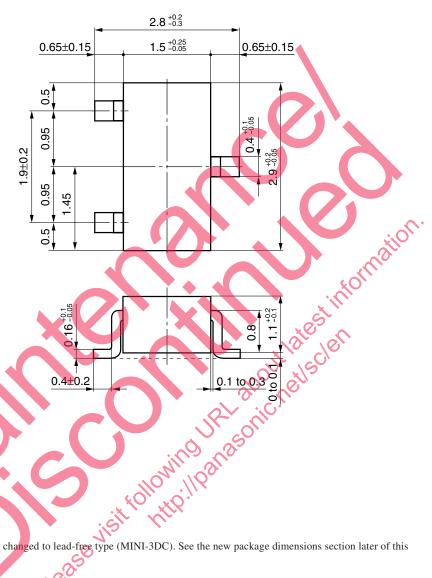
TO-92 type package



Note) The package will be changed to lead-free type (SSIP003-P-0000S). See the new package dimensions section later of this datasheet.

■ Package Dimensions (Unit: mm)(continued)

Mini type package



Note) The package will be changed to lead-free type (MINI-3DC). See the new package dimensions section later of this datasheet.

■ Reference Characteristics

The following characteristics curves represent results from a specific sample therefore they do not guarantee the characteristics for the final product.

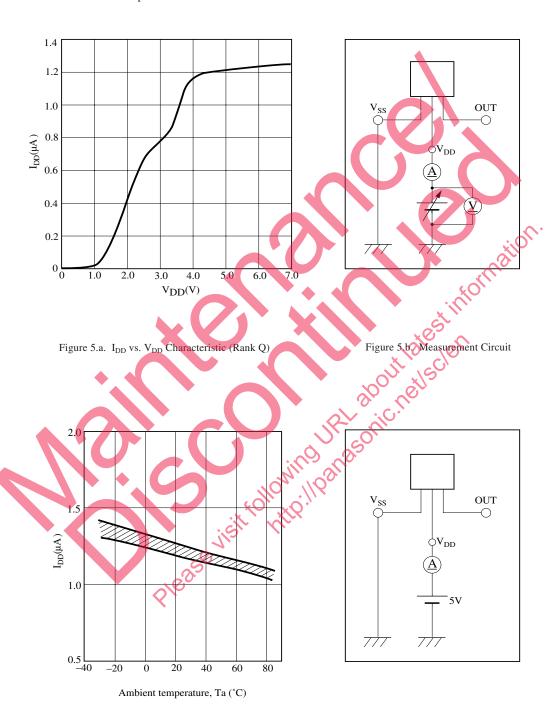
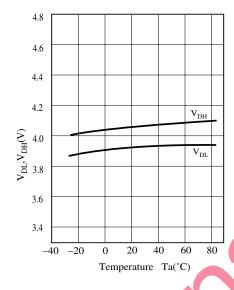


Figure 6.a. I_{DD} Temperature Characteristic (Rank Q)

Figure 6.b. Measurement Circuit

■ Reference Characteristics (continued)



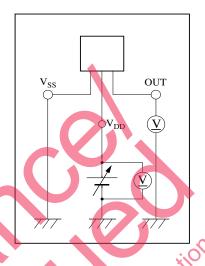
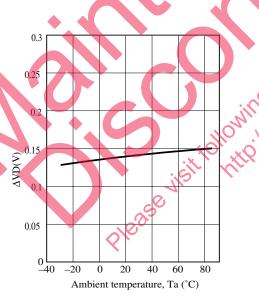


Figure 7.a. V_{DL}/V_{DH} Temperature Characteristic (Rank Q



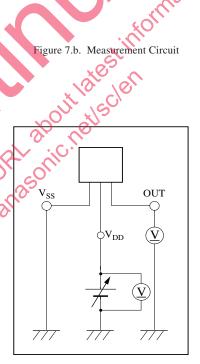
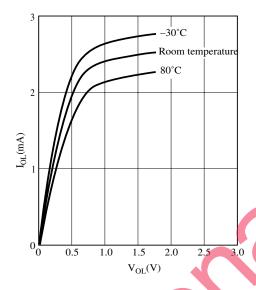


Figure 8.a. ΔVD Temperature Characteristic (Rank Q)

Figure 8.b. Measurement Circuit

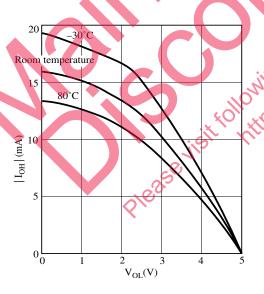
■ Reference Characteristics (continued)



V_{SS} OUT V_{DB} A

Figure 9.a. I_{OL} vs. V_{OL} Characteristic

Figure 9.b. Measurement Circuit



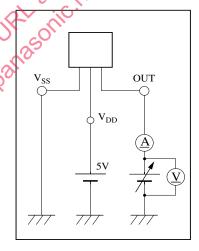
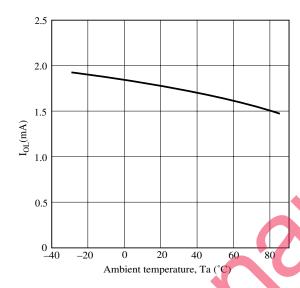


Figure 10.a. I_{OH} vs. V_{OH} Characteristic

Figure 10.b. Measurement Circuit

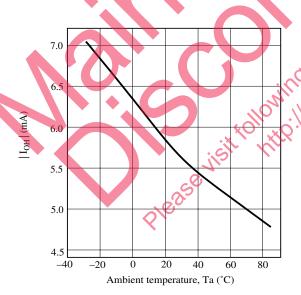
■ Reference Characteristics (continued)



V_{SS} OUT A

Figure 11.a. I_{OL} vs. Temperature Characteristic

Figure 11.b. Measurement Circuit



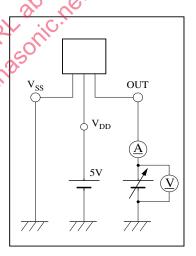


Figure 12.a. I_{OH} vs. Temperature Characteristic

Figure 12.b. Measurement Circuit

■ TO-92 Type Package Taping-Specifications (MN1381/MN13811/MN13812)

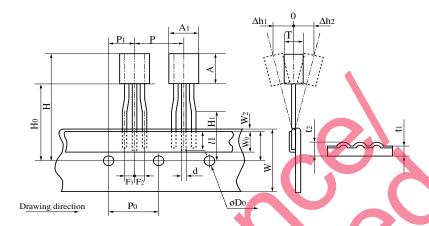


Figure 13. TO-92 Type Package Taping-Dimensions (Ammunition pack)

TO-92 Type Package Taping Dimensions (Ammunition pack)

Name	Symbol	Length (mm)
Product height*	A	5.3 max
Product width*	A1	5.2 max
Product thickness*	T	4.2 max
Lead width*	d	$0.45^{+0.15}_{-0.1}$
Taped lead length	<i>I</i> 1	2.0 max
Product pitch	P	12.7±1.0
Feed hole pitch	P0	12.7±0.3
Feed hole position	P1	6.35±0.5
Lead spacing	F1, F2	2.5 +0.5 - 0.2
Product deflection angle	Δh1, Δh2	2.0 max
Tape width	W	18.0 +1.0

Name	Symbol	Length (mm)
Adhesive tape width	W0	6.0±0.5
Feed hole position	W1	9.0±0.5
Adhesive tape position	O WO	0.5 max
Distance to top of product	15 H	25.0 max
Distance to bottom of product	H0	19.0±0.5
Lead clinch height	H1	16.0±0.5
Feed hole diameter	D0	4.0±0.2
Tape thickness	t1	0.7±0.2
Total tape thickness	t2	1.5 max
. / ,		

Note*1: For further details, see the specifications issued separately.

	0/6/	
W	Н	D
330	250	41

Unit: mm

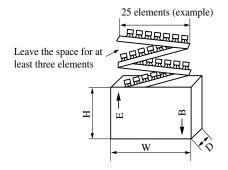
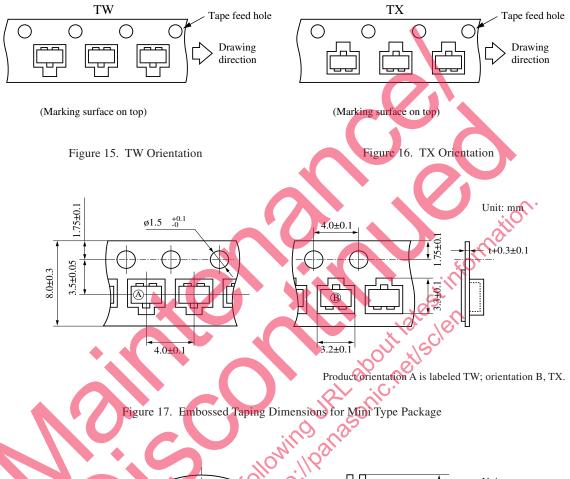


Figure 14. Box Dimensions for TO-92 Type Packages with Ammunition pack

■ Embossed Taping Specifications for Mini Type Package (MN1382/MN13821/MN13822)

There is a choice of two orientations, TW and TX, for the product relative to the tape.



021±0.8

Unit: mm

5:07 + 8 L 1 8

10±1.5

3,000 packages per reel

Figure 18. Embossed Taping Reel Dimensions for Mini Type Package

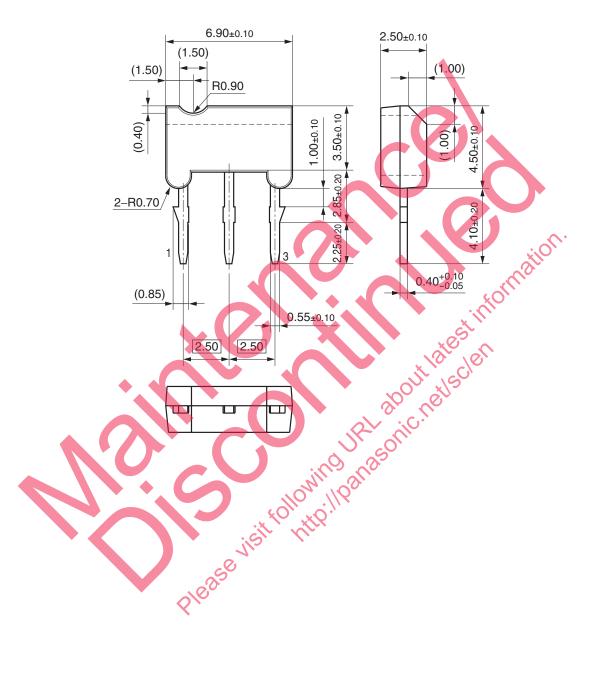
■ Reliability Testing Results for MN1380 Series

(1) M type package (MN1380/MN13801/MN13802) and TO-92 type package (MN1381/MN13811/MN13812)

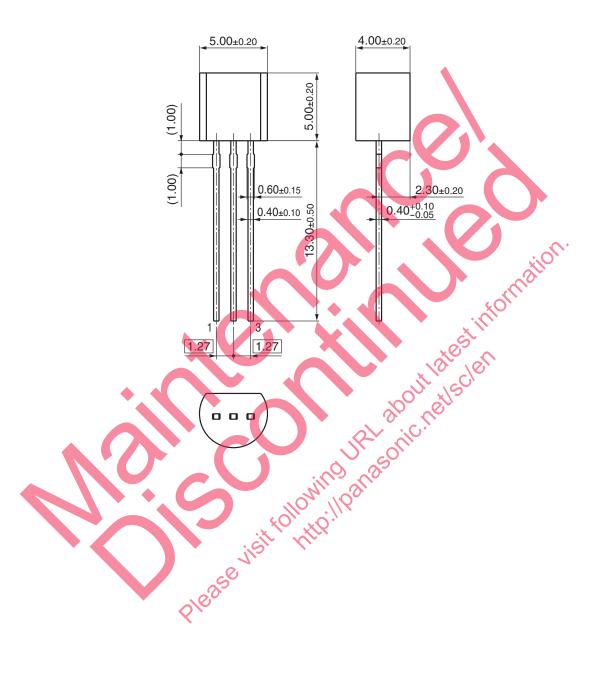
Test Subjects	Test Conditions	Results
Operating lifetime test	V_{DD} =5.5V, Ta=125°C, t=1000hrs	0/15
High-temperature storage test	Ta=150°C, t=1000hrs	0/15
Low-temperature storage test	Ta=-65°C, t=1000hrs	0/15
High-temperature,	Ta=85°C, RH=85%, t=1000hrs	0/15
high-humidity storage test		
High-temperature,	V _{DD} =5.5V, Ta=85°C, RH=85%, t=1000hrs	0/15
high-humidity bias test		
Thermal shock test	Ta=150°C and -65°C.	0/15
	Five minutes at each temperature for ten cycles	
Temperature cycle test	Ta=150°C and -65°C.	0/15
	Thirty minutes at each temperature for ten cycles	
Pressure cooker test	Two atmospheres for 50 hours at ambient temperature (Ta) of 121°C	0/15
Soldering test	Ambient temperature (Ta) of 230°C for five seconds	0/15
Solder heat resistance test	Ambient temperature (Ta) of 270°C for ten seconds	0/15
2) Mini type package (MN1382/N	MN13821/MN13822)	N. C.
Test Subjects	Test Conditions	Results
Operating lifetime test	V _{DD} =5.5V, Ta=125°C, t=1000hrs	0/15
High-temperature storage test	Ta=150°C, t=1000hrs	0/15
Low-temperature storage test	Ta=-65°C, t=1000hrs	0/15
High-temperature,	Ta=85°C, RH=85%, t=1000hrs	0/15
high-humidity storage test	011,150	
High-temperature,	V _{DD} =5.5V, Ta=85°C, RH=85%, t=1000hrs	0/15
high-humidity bias test		
Thermal shock test	Ta=150°C and -65°C.	0/15
	Five minutes at each temperature for ten cycles	
	Ta=150°C and -65°C	0/15
Temperature cycle test	14-150 € tild 05 €.	
Temperature cycle test	Thirty minutes at each temperature for ten cycles	
Temperature cycle test Pressure cooker test *1		0/15
	Thirty minutes at each temperature for ten cycles	0/15 0/15

Note*1: Note that the testing conditions for the mini package differ from those for the other two packages.

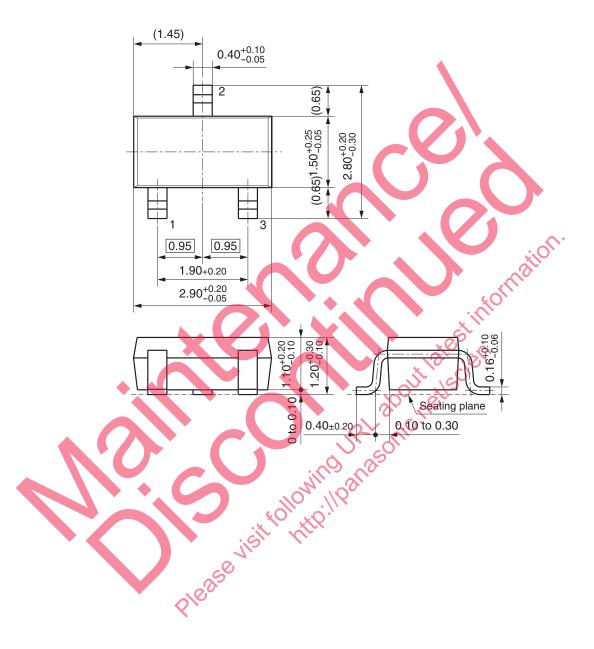
- New Package Dimensions (Unit: mm)
- M3A (Lead-free package)



- New Package Dimensions (Unit: mm)(continued)
- SSIP003-P-0000S (Lead-free package)



- New Package Dimensions (Unit: mm)(continued)
- MINI-3DC (Lead-free package)



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